

NCP51145

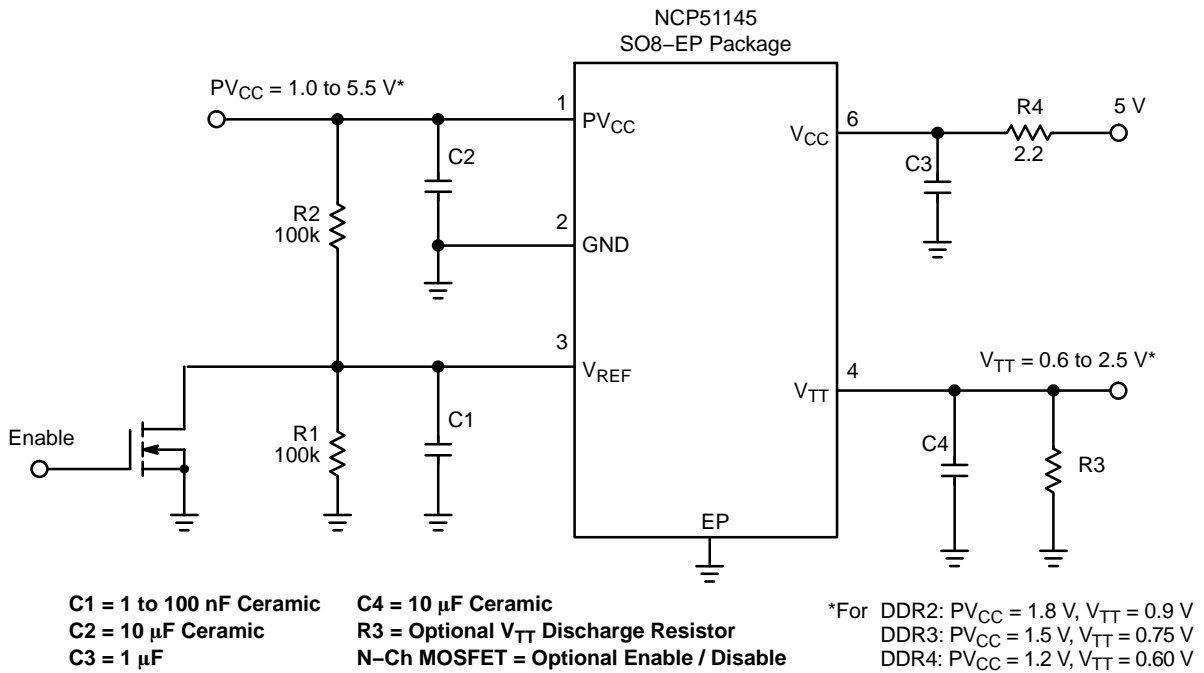


Figure 1. Application Diagram

PIN FUNCTION DESCRIPTION

Pin No. SO8-EP	Pin No. DFN8	Pin Name	Description
1	1	PV _{CC}	Input voltage which supplies current to the output pin. $C_{IN} \cong \frac{1}{2} \cdot C_{OUT}$
2	4	GND	Common Ground
3	5	V _{REF}	Buffered reference voltage input equal to $\frac{1}{2}$ of V _{DDQ} and active low shutdown pin. An external resistor divider dividing down the PV _{CC} voltage creates the regulated output voltage. Pulling the pin to ground (0.15 V maximum) turns the device off.
4	2	V _{TT}	Regulator output voltage capable of sourcing and sinking current while regulating the output rail. C _{OUT} = 10 μF Ceramic, or greater
5, 7, 8	3, 7	NC	True No Connect
6	8	V _{CC}	The V _{CC} pin is a 5 V input pin that provides internal bias to the controller. PV _{CC} should always be kept lower or equal to V _{CC} .
-	6	V _{TTS}	V _{TT} Sense
EP	EP	EPAD	Pad for thermal connection. The exposed pad must be connected to the ground plane using multiple vias for maximum power dissipation performance.

NCP51145

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input Supply Voltage Range ($V_{CC} \geq PV_{CC}$) (Note 1)	PV_{CC}, V_{CC}	-0.3 to 6	V
Output Voltage Range	V_{TT}	-0.3 to 6	V
Reference Input Range	V_{REF}	-0.3 to 6	V
Maximum Junction Temperature	$T_{J(max)}$	150	°C
Storage Temperature Range	TSTG	-65 to 150	°C
ESD Capability, Human Body Model (Note 2)	ESDHBM	2	kV
ESD Capability, Machine Model (Note 2)	ESDMM	200	V
Lead Temperature Soldering Reflow (SMD Styles Only), Pb-Free Versions (Note 3)	T_{SLD}	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
2. This device series incorporates ESD protection and is tested by the following methods:
ESD Human Body Model tested per AEC-Q100-002 (EIA/JESD22-A114)
ESD Machine Model tested per AEC-Q100-003 (EIA/JESD22-A115)
Latchup Current Maximum Rating: ≤ 150 mA per JEDEC standard: JESD78
3. For information, please refer to our Soldering and Mounting Techniques Reference Manual, SOLDERRM/D

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Characteristics, SO8-EP (Note 4) Thermal Resistance, Junction-to-Air (Note 5) Thermal Reference, Junction-to-Lead2 (Note 5)	$R_{\theta JA}$ $R_{\psi JL}$	82 TBD	°C/W

4. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
5. Values based on copper area of 645 mm² (or 1 in²) of 1 oz copper thickness and FR4 PCB substrate.

OPERATING RANGES (Note 6)

Rating	Symbol	Min	Max	Unit
Input Voltage	PV_{CC}	1.0	5.5	V
Bias Supply Voltage	V_{CC}	4.75	5.25	V
Ambient Temperature	T_A	-40	85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

6. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.

NCP51145

ELECTRICAL CHARACTERISTICS

$PV_{CC} = 1.8\text{ V} / 1.5\text{ V}$; $V_{CC} = 5\text{ V}$; $V_{REF} = 0.9\text{ V} / 0.75\text{ V}$; $C_{TT} = 10\text{ }\mu\text{F}$ (Ceramic), $T_A = +25^\circ\text{C}$, unless otherwise specified.

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
-----------	-----------------	--------	-----	-----	-----	------

REGULATOR OUTPUT

Output Offset Voltage	$I_{out} = 0\text{ A}$	V_{OS}	-16	-	+16	mV
Load Regulation	$I_{out} = \pm 1.8\text{ A}$, $PV_{CC} = 1.8\text{ V}$, $V_{REF} = 0.9\text{ V}$	Reg_{load}	-4	-	+4	mV
	$I_{out} = \pm 1.5\text{ A}$, $PV_{CC} = 1.5\text{ V}$, $V_{REF} = 0.75\text{ V}$					
	$I_{out} = \pm 1.2\text{ A}$, $PV_{CC} = 1.35\text{ V}$, $V_{REF} = 0.675\text{ V}$					
	$I_{out} = \pm 1.2\text{ A}$, $PV_{CC} = 1.2\text{ V}$, $V_{REF} = 0.6\text{ V}$					

INPUT AND STANDBY CURRENTS

Bias Supply Current	$I_{out} = 0\text{ A}$	I_{BIAS}	-	1	2.5	mA
Standby Current	$V_{REF} < 0.2\text{ V}$ (Shutdown), $R_{LOAD} = 180\Omega$	I_{STB}	-	2	90	μA

CURRENT LIMIT PROTECTION

Current Limit	$PV_{CC} = 1.8\text{ V}$, $V_{REF} = 0.9\text{ V}$	I_{LIM}	2	-	3.5	A
	$PV_{CC} = 1.5\text{ V}$, $V_{REF} = 0.75\text{ V}$		1.5	-	3.5	

SHUTDOWN THRESHOLDS

Shutdown Threshold Voltage	Enable	V_{IH}	0.45	-	-	V
	Shutdown	V_{IL}	-	-	0.15	

THERMAL SHUTDOWN

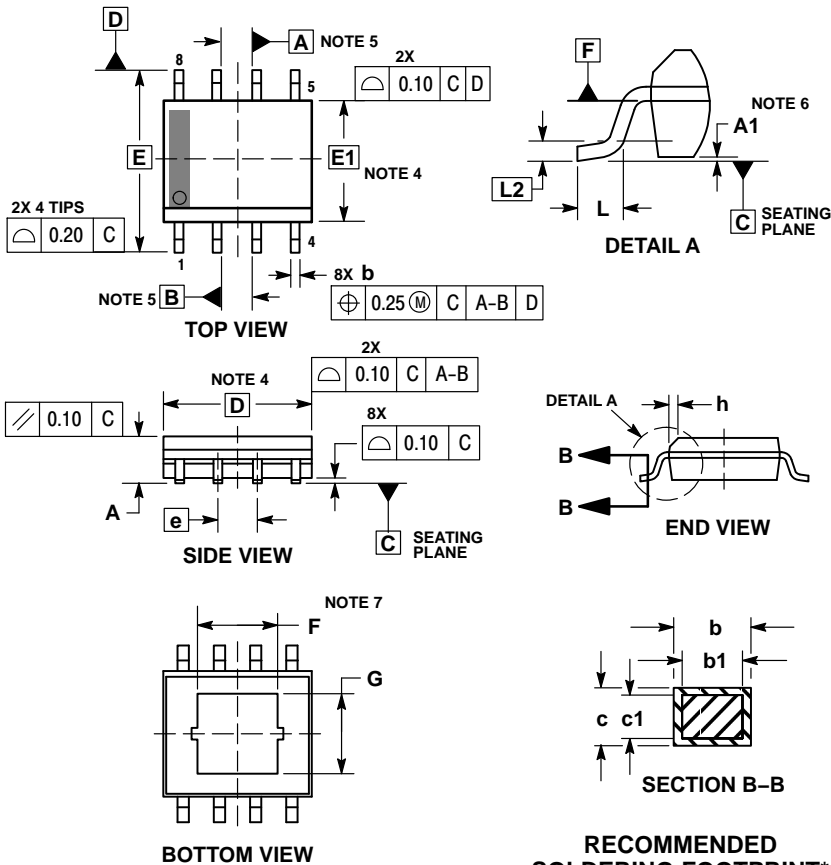
Thermal Shutdown Temperature	$V_{CC} = 5\text{ V}$	T_{SD}	-	125	-	$^\circ\text{C}$
Thermal Shutdown Hysteresis	$V_{CC} = 5\text{ V}$	T_{SH}	-	35	-	$^\circ\text{C}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NCP51145

PACKAGE DIMENSIONS

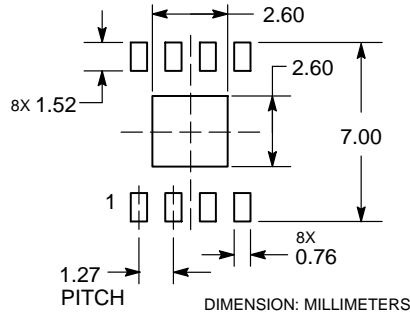
SOIC8-NB EP CASE 751BU ISSUE E



- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 - CONTROLLING DIMENSION: MILLIMETERS.
 - DIMENSION *b* DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
 - DIMENSION *D* DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE. DIMENSION *E* DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE. DIMENSIONS *D* AND *E* ARE DETERMINED AT DATUM *F*.
 - DIMENSIONS *A* AND *B* ARE TO BE DETERMINED AT DATUM *F*.
 - A1* IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
 - TAB CONTOUR MAY VARY MINIMALLY TO INCLUDE TOOLING FEATURES.

DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.00	0.10
b	0.31	0.51
b1	0.28	0.48
c	0.17	0.25
c1	0.17	0.23
D	4.90 BSC	
E	6.00 BSC	
E1	3.90 BSC	
e	1.27 BSC	
F	1.55	2.39
G	1.55	2.39
h	0.25	0.50
L	0.40	1.27
L2	0.25 BSC	

RECOMMENDED SOLDERING FOOTPRINT*

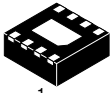


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

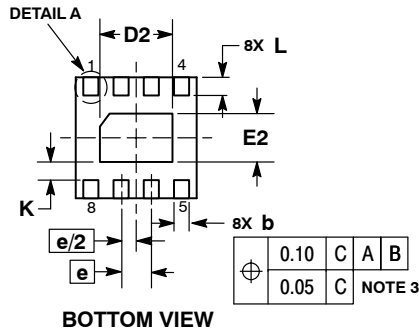
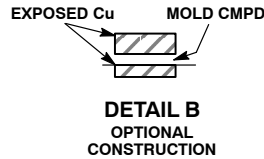
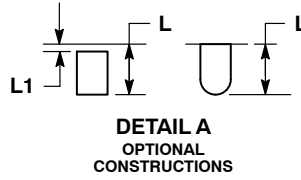
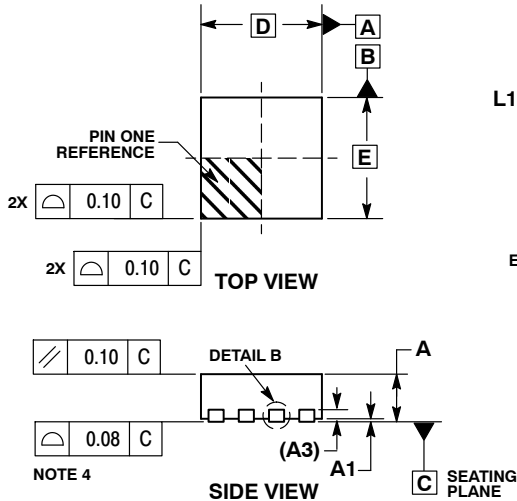
ON Semiconductor®



SCALE 4:1

DFN8 2x2, 0.5P
CASE 506AA-01
ISSUE E

DATE 22 JAN 2010

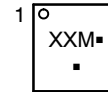


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	2.00	BSC
D2	1.10	1.30
E	2.00	BSC
E2	0.70	0.90
e	0.50	BSC
K	0.30	REF
L	0.25	0.35
L1	---	0.10

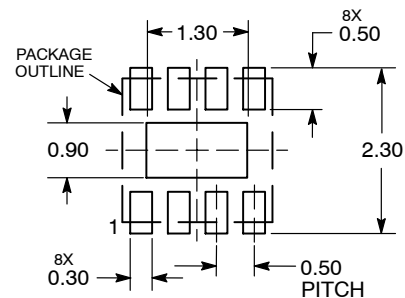
GENERIC MARKING DIAGRAM*



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Device

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON18658D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	DFN8, 2.0X2.0, 0.5MM PITCH	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:
Voice Mail: 1 800-282-9855 Toll Free USA/Canada
Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[onsemi:](#)

[NCP51145PDR2G](#) [NCP51145MNTAG](#)